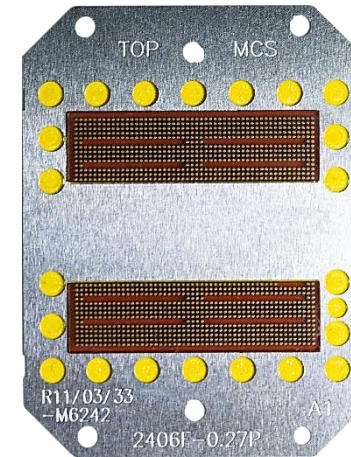
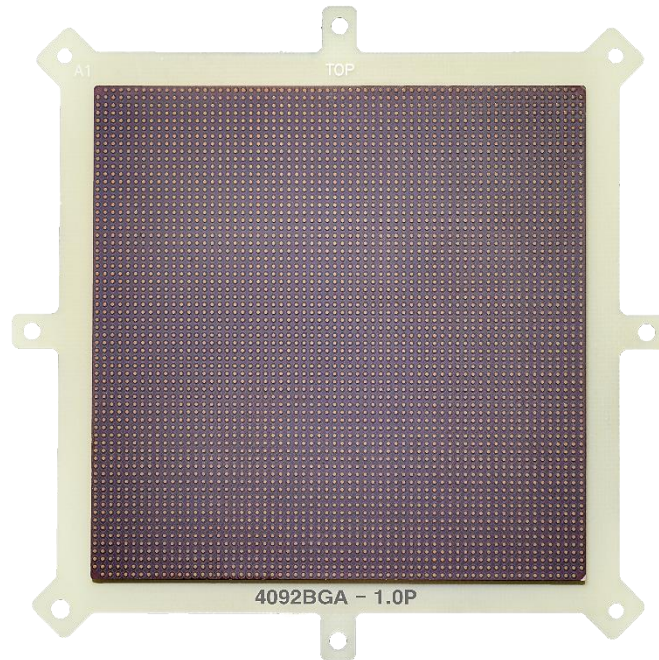


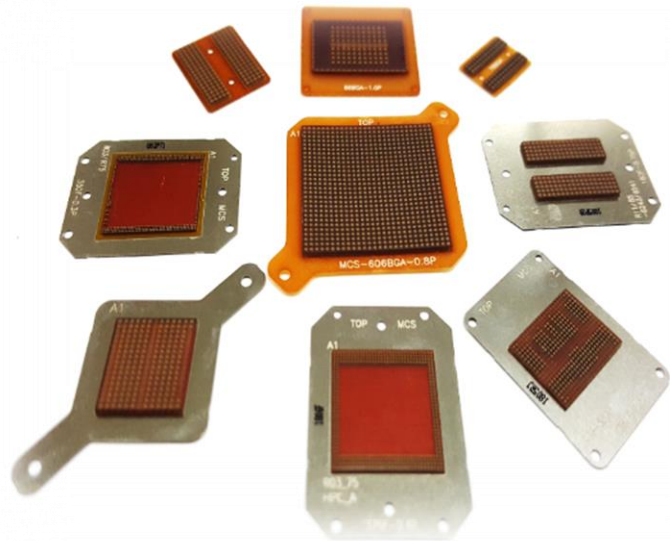
Company Presentation



Leading-edge in Test Socket Technology

The best in test solution technology
Excellence and Distinction in the technology
Products & Services with customer satisfaction

Jan. 2022



CONTENTS

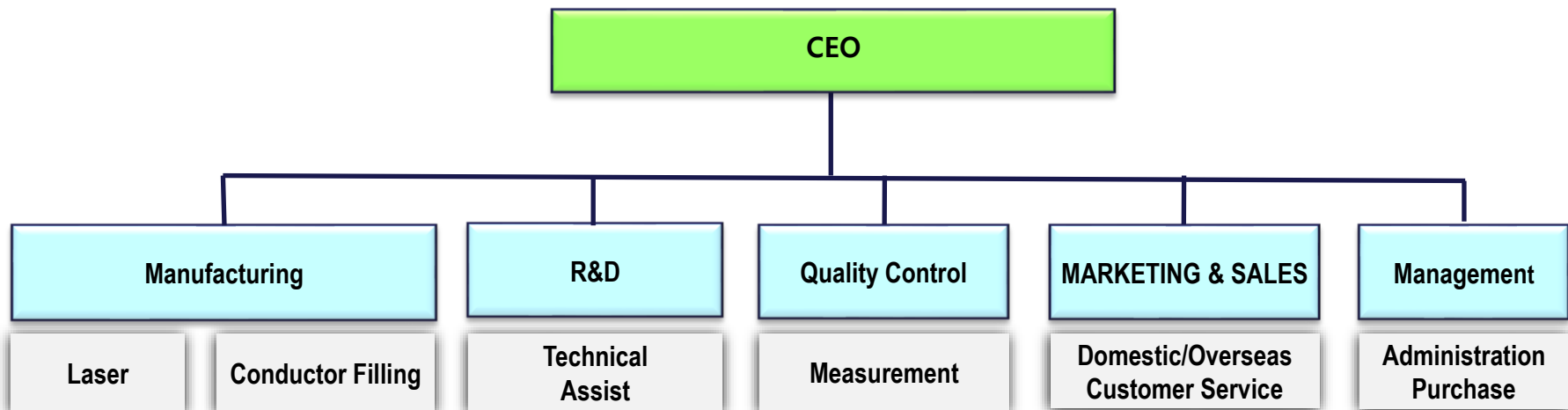
1. INTRODUCTION

2. PRODUCTS

3. PATENT

INTRODUCE

Name	Micro Sensing Lab
Establish	December 2004
President	Oh Seong Kyung
Business	PCR Socket
Employee	30
Address	105-31, Sinsaunjeon-gil, Seongnam-myeon Dongnam-gu, Cheonan-si, Chungnam-do, 31245, Korea
Web	www.mslltd.co.kr



INTRODUCTION

2004. 12	• Establish
2005. 06	• Venture business Certification
2006. 12	• Register factory
2007. 01	• Enterprise Research Certification
2009. 06	• Parts specialized company Certification
2010. 10	• Inno-biz Certification
2011. 12	• Company name changed to Ak-innotech, Inc
2012. 10	• ISO 9001 Certification
2013. 10	• MCS investment shares
2014. 03	• Start providing PCR to Samsung Electronics
2017. 07	• Company name changed to Micro Sensing Lab, Inc
2018. 05	• Completed the development of fine pitch (0.2mm)

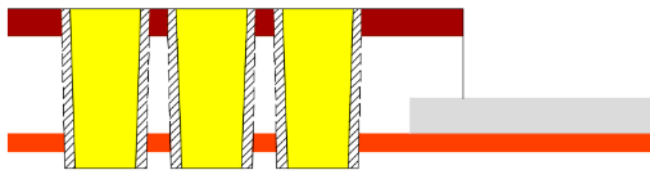
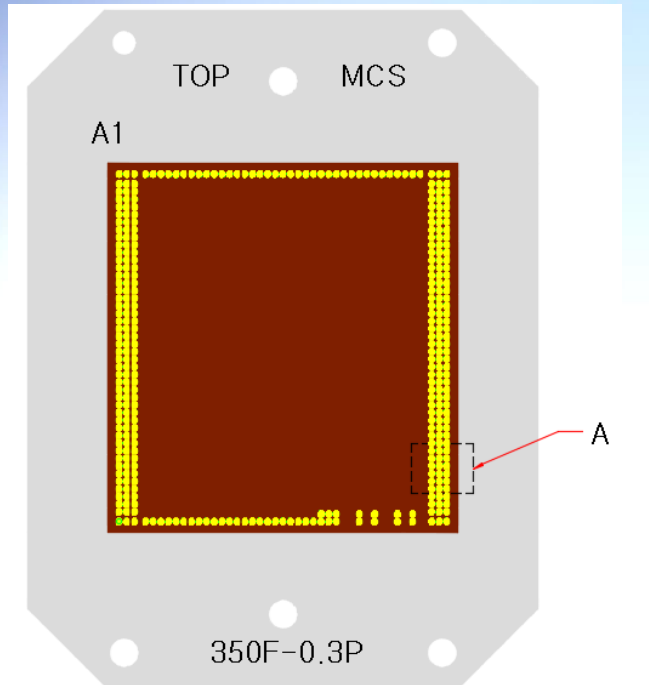
INTRODUCTION

The Certification

- Venture business Certification
- Enterprise Research Certification
- Parts specialized company Certification
- Inno-biz Certification
- ISO 9001 Certification
- Excellent firm employment in Gwang-Ju city

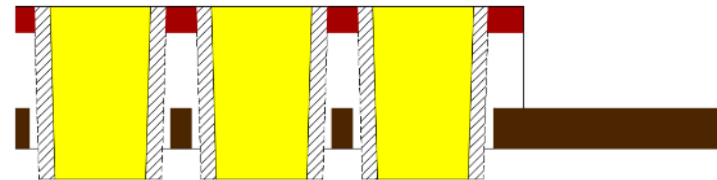
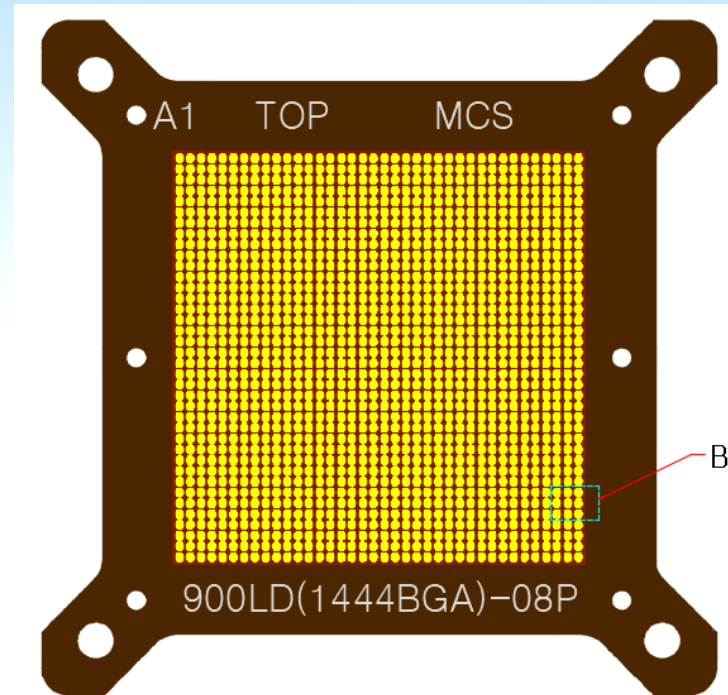


SUS Frame (BGA)



A Cross section Detail

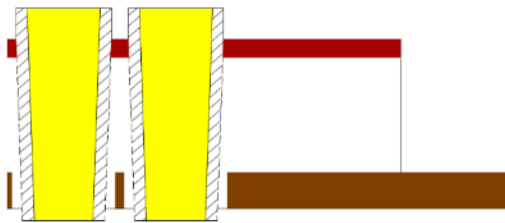
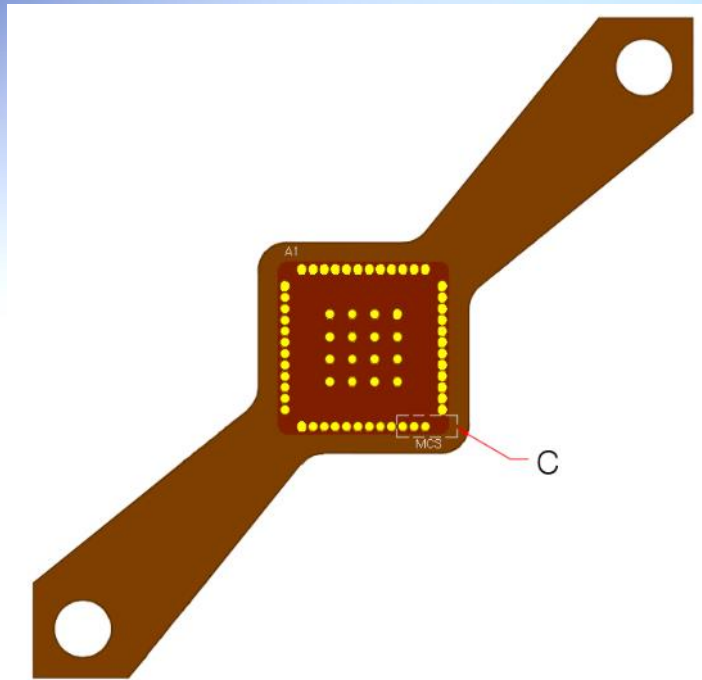
Epoxy Frame (BGA)



B Cross section Detail

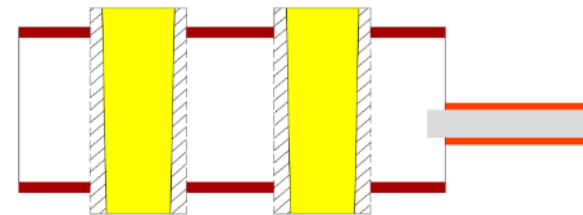
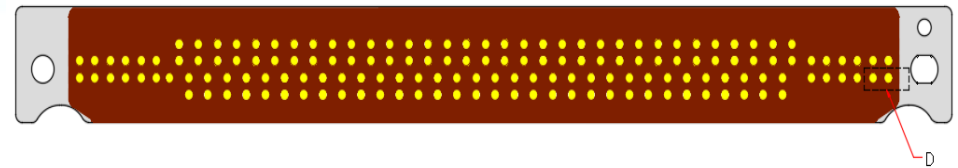
PRODUCTS _ LGA & INTERPOSER

Epoxy Frame (LGA)



C Cross section Detail

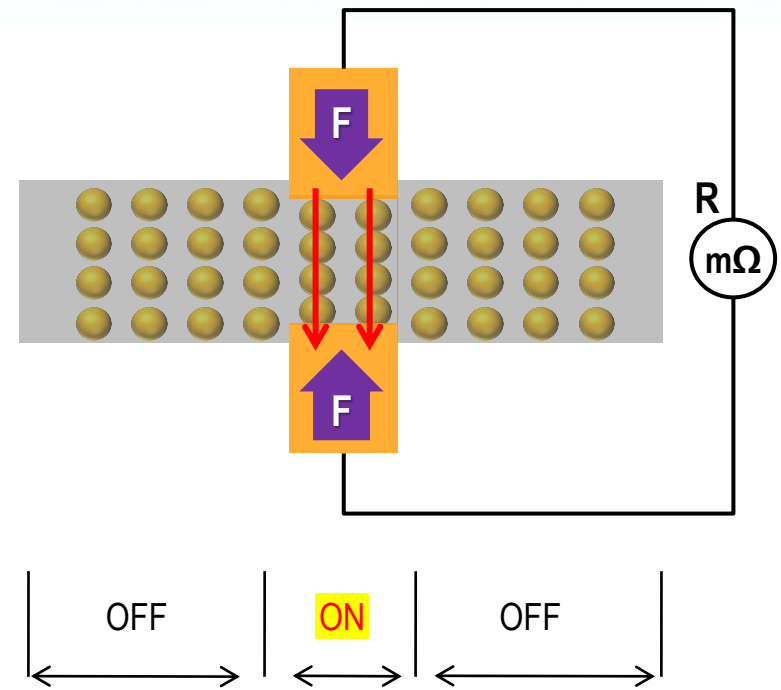
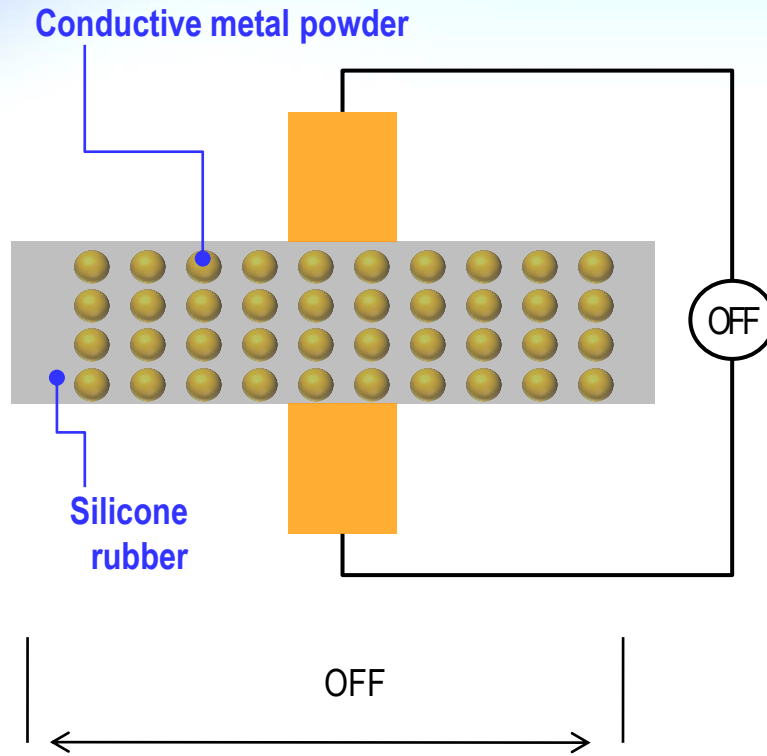
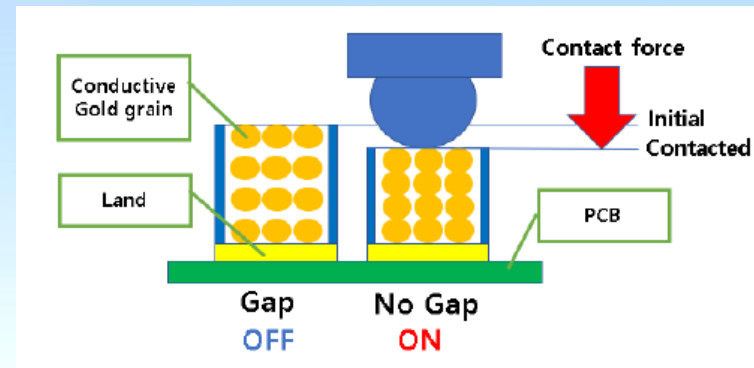
SUS Frame (INTERPOSER)



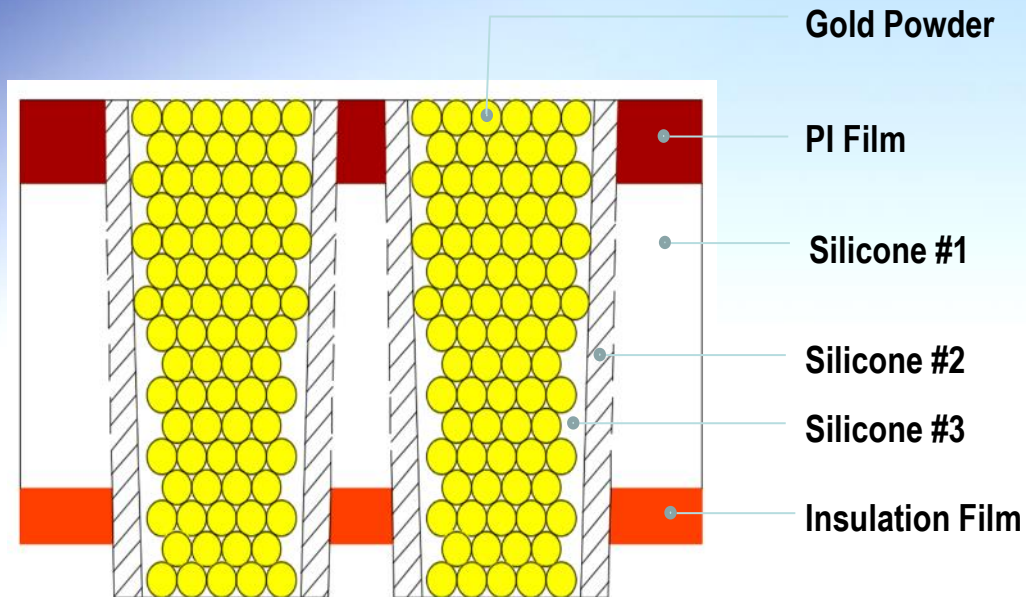
D Cross section Detail

PRODUCTS _ STRUCTURE

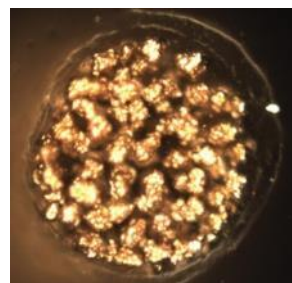
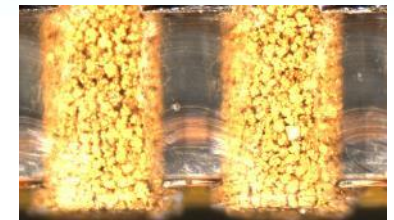
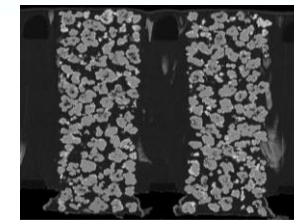
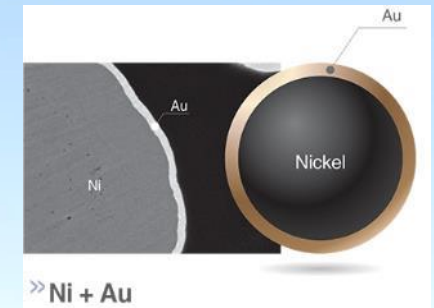
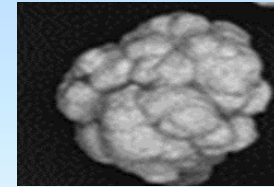
■ Mechanism of Rubber socket



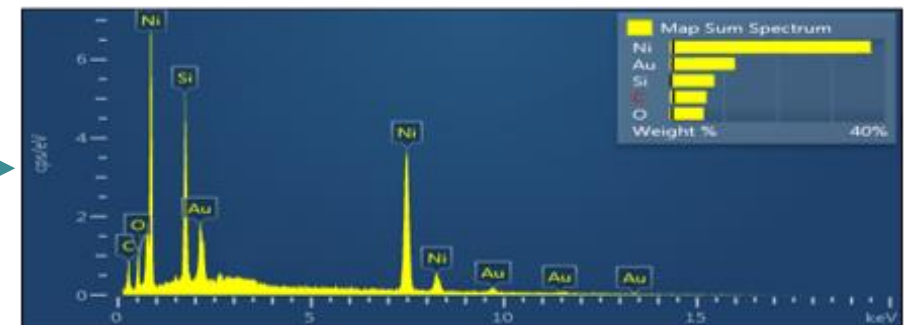
PRODUCTS _ STRUCTURE



Cross Section Detail

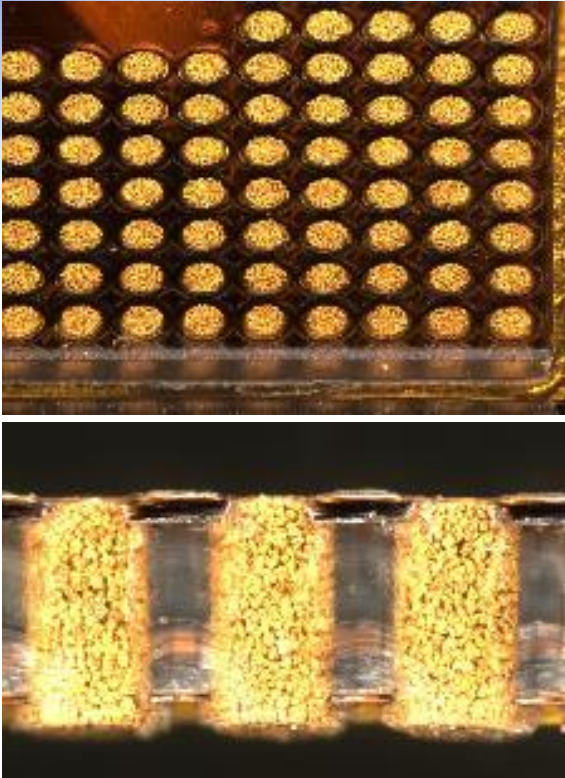


Component Analysis(SEM)



PRODUCTS _ STRUCTURE

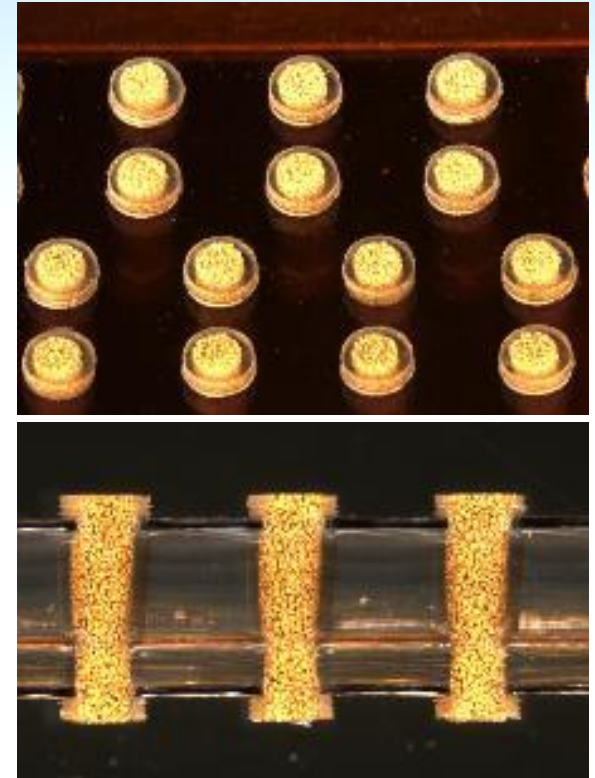
[BGA]



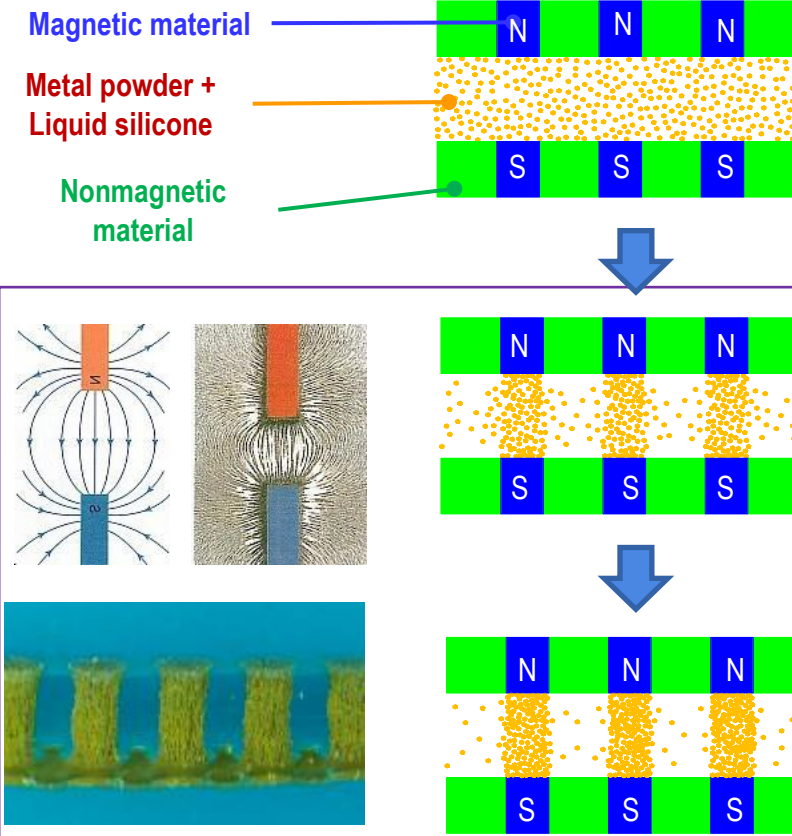
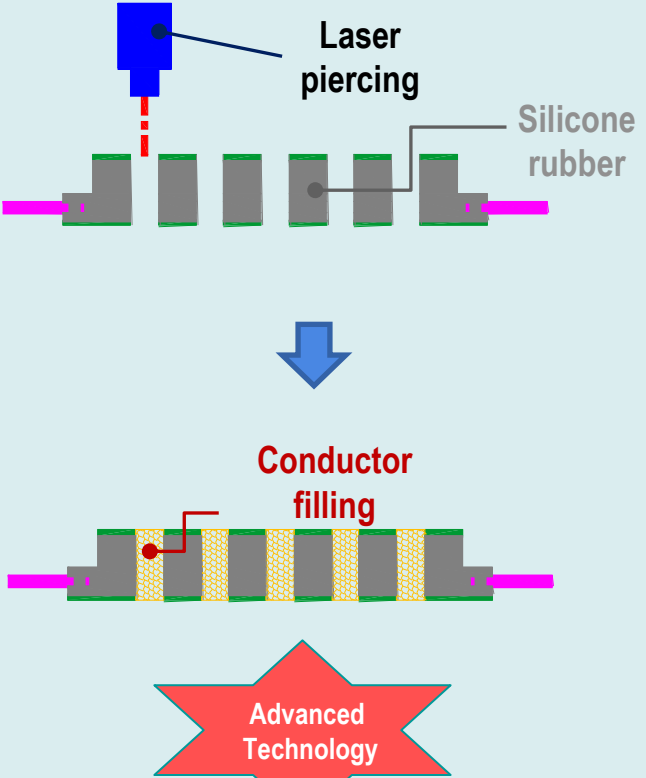
[LGA/QFN]



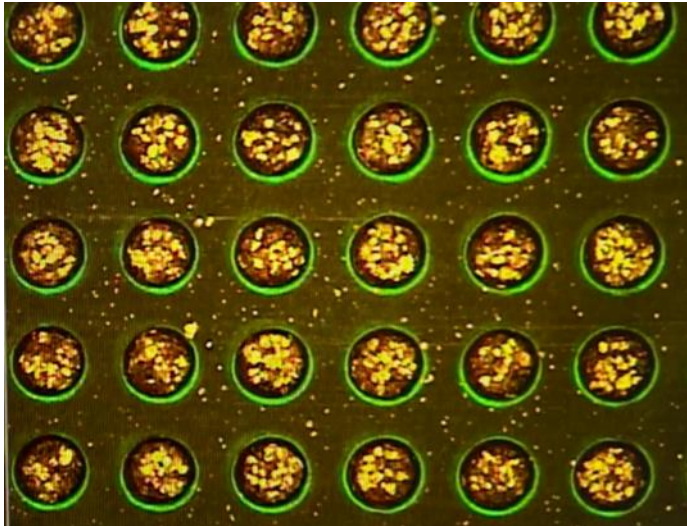

[INTERPOSER]



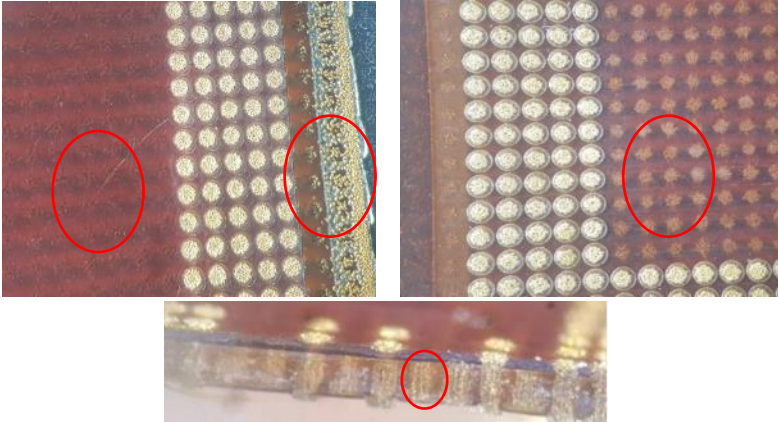
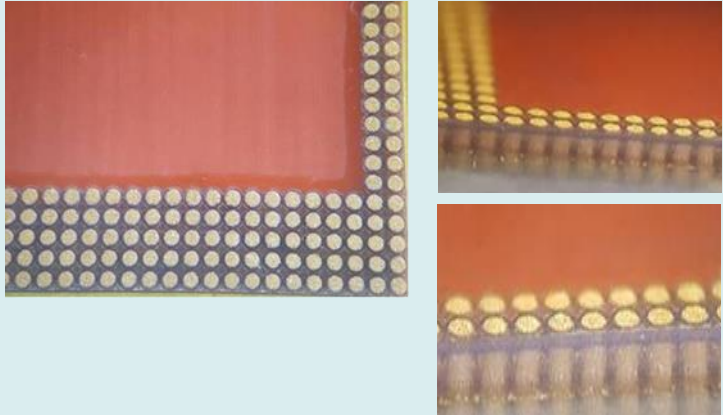
PRODUCTS _ Technology

	Magnetic Field Molding Method [M F M]	Laser Hole Filling Method [L H F]
Theory	<p> Magnetic material ——— N N N Metal powder + Liquid silicone ——— Nonmagnetic material ——— S S S </p>  <p>The diagram illustrates the MFM process in three stages. The top stage shows the initial layers: a top magnetic material layer with North (N) poles, a middle layer of metal powder and liquid silicone, and a bottom nonmagnetic material layer with South (S) poles. A blue arrow points to the second stage, which shows the magnetic field lines (represented by curved arrows) and a microscopic image of the mold surface. A second blue arrow points to the third stage, which shows the final patterned structure with vertical pillars.</p>	 <p>The diagram illustrates the LHF process in two stages. The top stage shows a laser piercing a hole through a layer of silicone rubber. A blue arrow points to the second stage, which shows the resulting structure with the hole filled with a conductor. A red starburst labeled 'Advanced Technology' is positioned below the second stage.</p>
Maker	Competitor	MCS

PRODUCTS _ Technology

	Magnetic Field Molding Method [M F M]	Laser Hole Filling Method [L H F]
Gold Powder	<ul style="list-style-type: none">✓ Gold powder residue could be remained among conductive holes by MFM process✓ It could induce leakage and poor high frequency performance	<ul style="list-style-type: none">✓ No gold powder residue remained through LHF process
		
Maker	Competitor	MCS

PRODUCTS _ Technology

	Magnetic Field Molding Method [M F M]	Laser Hole Filling Method [L H F]
Tooling	<ul style="list-style-type: none"> ✓ Need tooling for each PKG's pitch and ball pattern 	<ul style="list-style-type: none"> ✓ Possible to make PCR by laser regardless of PKG's pitch and ball pattern ✓ No tooling is required
Gold Powder	<ul style="list-style-type: none"> ✓ Dummy powder pile at no test pin area ✓ Gold powder loss 	<ul style="list-style-type: none"> ✓ No loss of gold powder ✓ Laser hole drilling and filling gold powder for contact pin only 
Maker	Competitor	MCS

PRODUCTS _ TEFLON™ COATING PROPERTIES



Nonstick

Few solid substances adhere permanently to a Teflon™ coating. Tacky materials may stick temporarily, but almost all substances release easily



Low coefficient of friction

Teflon™ coatings lower the kinetic coefficient of friction to a range of 0.05 and 0.20, depending on the load, sliding speed, and coating.



Non-wetting

Teflon™ coatings resist water (hydrophobic) and oil (oleophobic). The low surface energy of the coatings creates cohesive forces strong enough to make water bead up and not spread across the coatings' surfaces.



Heat resistance

Teflon™ coatings can operate continuously at temperatures up to 260 °C (500 °F) and be used for intermittent service up to 316 °C (600 °F), with adequate ventilation, without affecting other properties.



Unique electrical properties

Teflon™ coatings have a high dielectric strength, low dissipation factor, and high surface resistivity over a wide range of frequencies. Adding fillers to certain coatings facilitates their use as anti-static coatings.



Low temp. durability

Most Teflon™ coatings retain their physical properties even at extremely low temperatures.

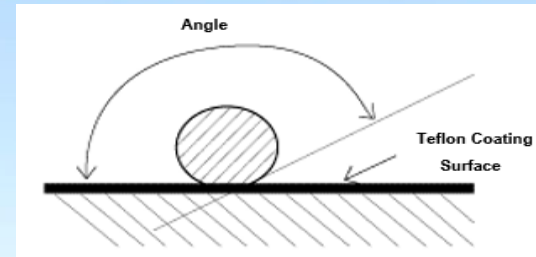
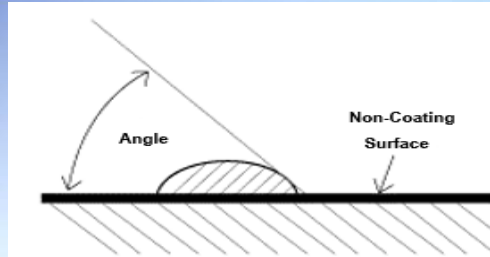
Teflon™ can also be considered for use at temperatures as low as -270°C.



Chemical resistance

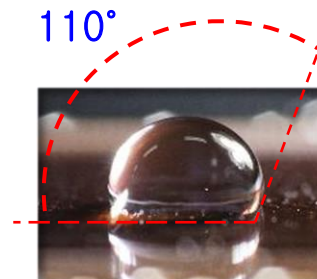
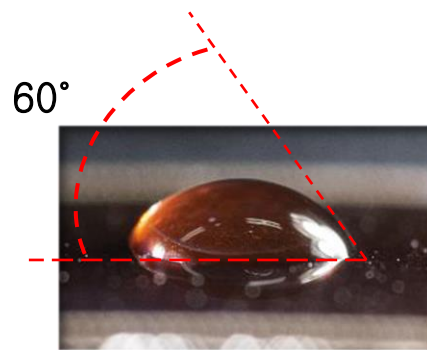
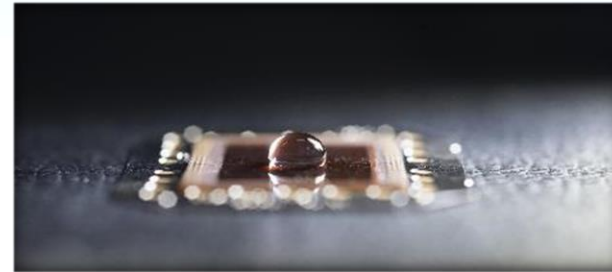
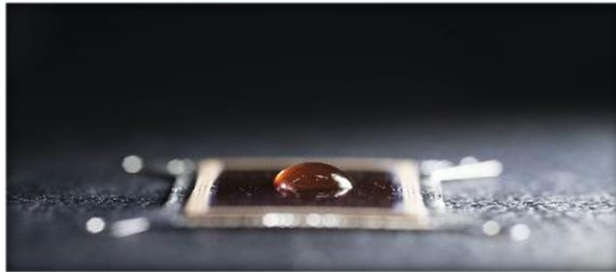
Because the low porosity of Teflon™ industrial coatings enables greater permeation resistance, chemical environments tend not to affect them. The only chemicals that may have a negative effect are molten alkali metals and highly reactive fluorinating agents.

PRODUCTS _ TEFLON™ COATING PROPERTIES





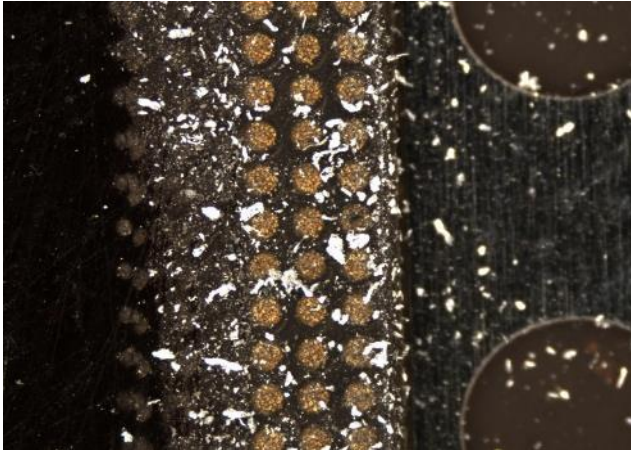

Normal PCR

Teflon Coating PCR



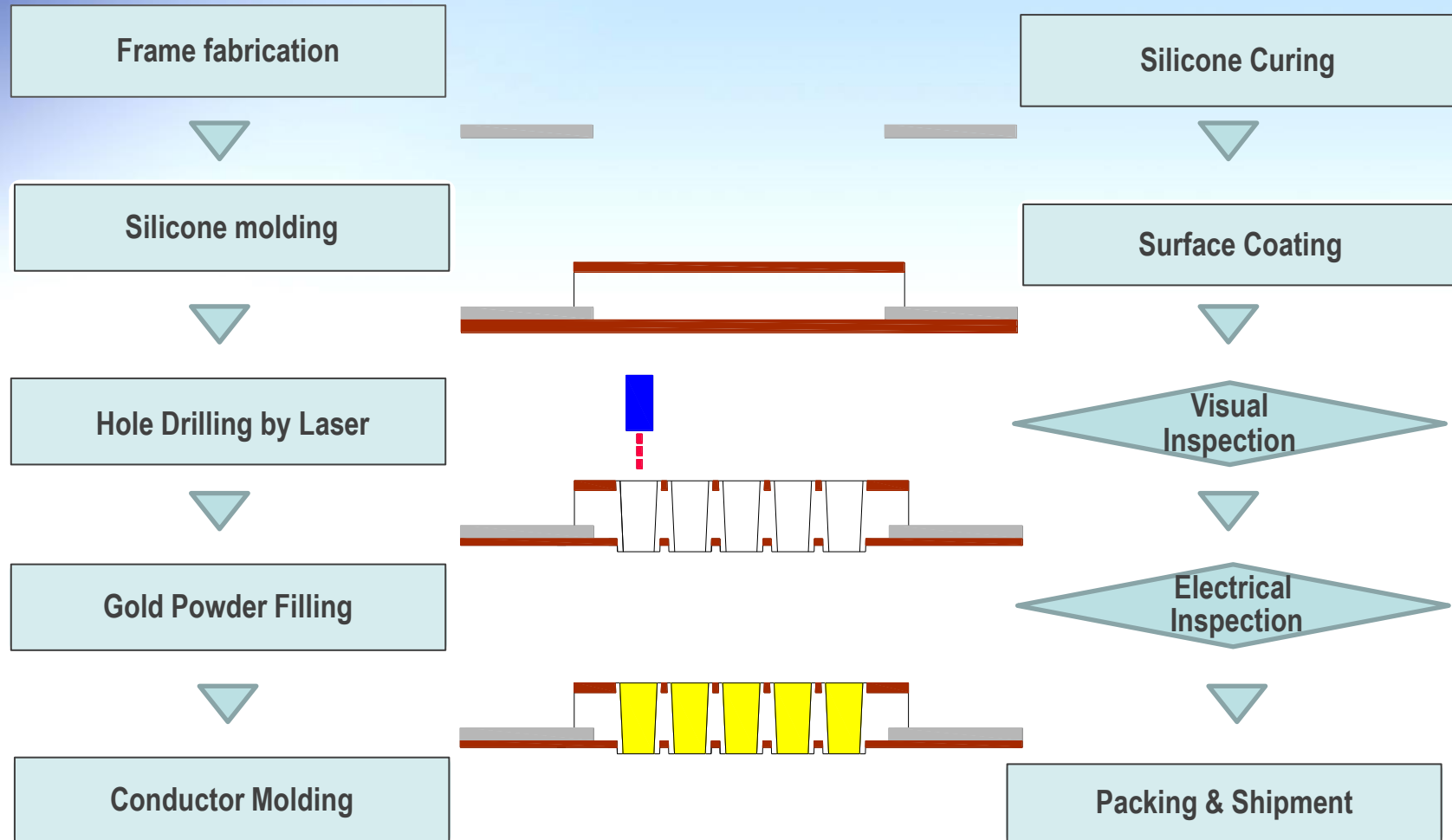
≤ Comparison of Non-cohesive by Contact Angle ≥

PRODUCTS _ TEFLON™ COATING PROPERTIES

	Before Cleaning	After Cleaning
Normal PCR		
Teflon Coating PCR		

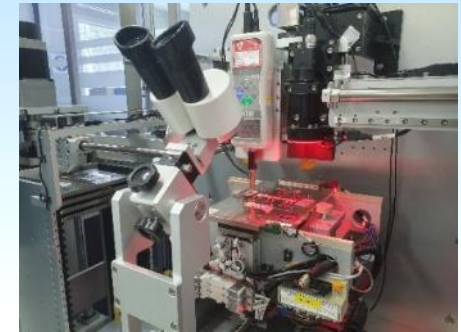
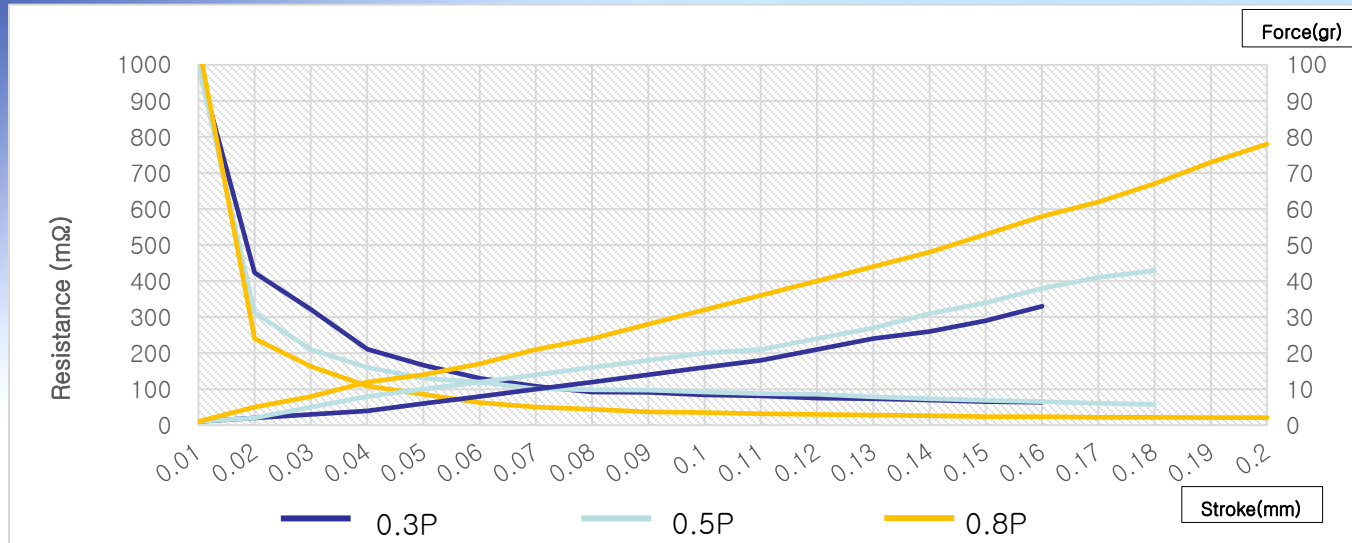
- ✓ (Test result shows) Teflon coating PCR is more easily cleaned and foreign materials on the top surface of the socket are more easily removed by dry air blowing due to non-sticky socket surface than Normal PCR.

PRODUCTS _ Manufacturing Process



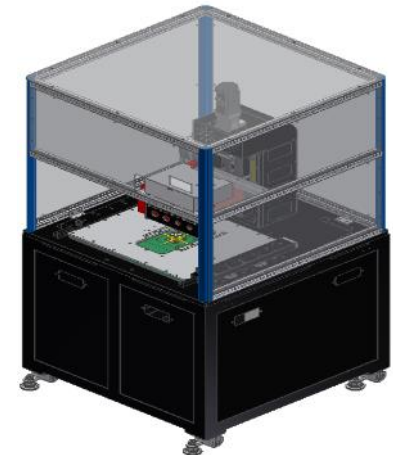
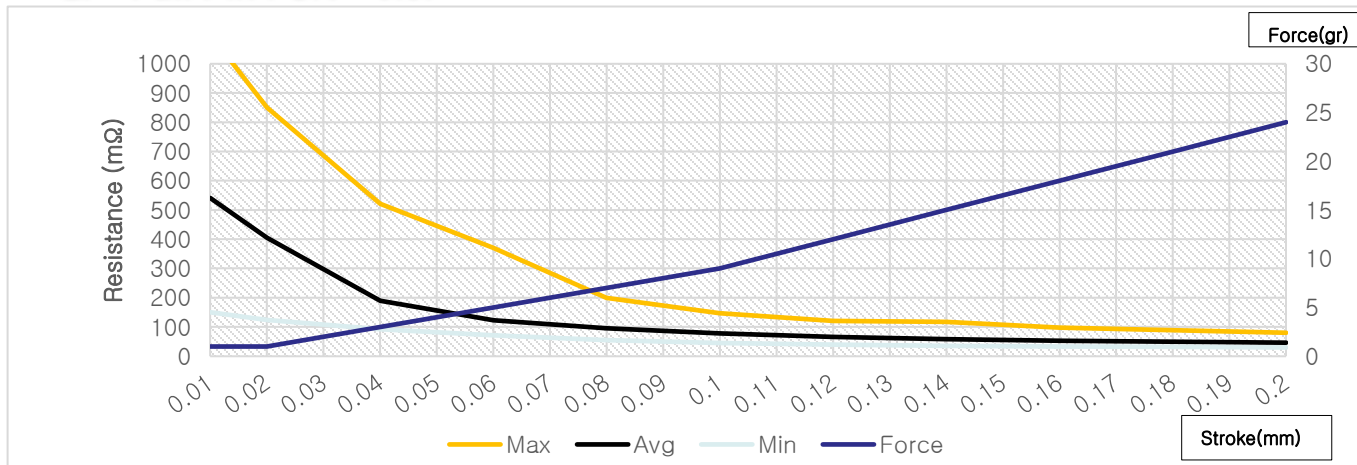
PRODUCTS _ Electric Performance(FSR)

1. 1Pin FSR



Inspection equipment : 1Pin

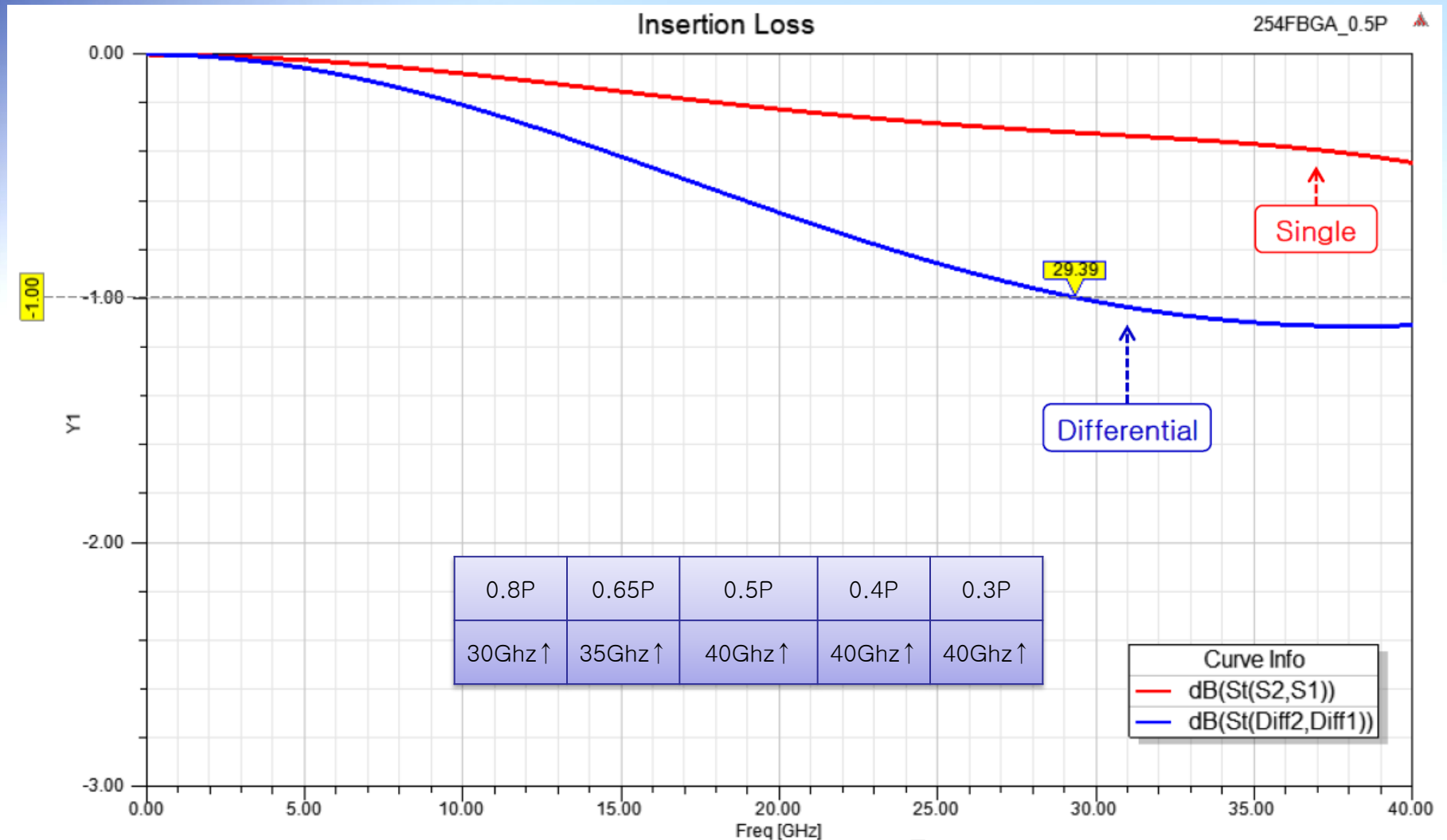
2. Full Pin FSR – 0.3P



Inspection equipment : Full Pin

PRODUCTS _ Electric Performance(SI)

Insertion Loss(S21) – Simulation



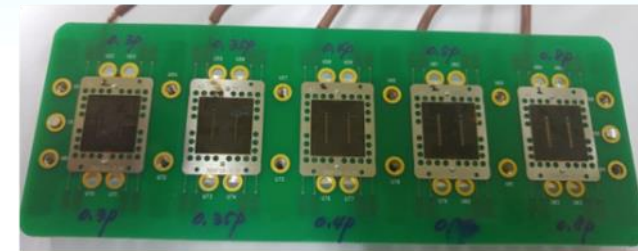
PRODUCTS _ Electric Performance(CCC)

1. Test socket

- Pitch : 0.30mm / 0.35mm / 0.40mm / 0.50mm / 0.80mm

2. Test method

- Test sample : 3Point measurement for each PCR
- Test equipment
 - DC power supply : UP-3020S
 - DC Electronic Load : SL-300

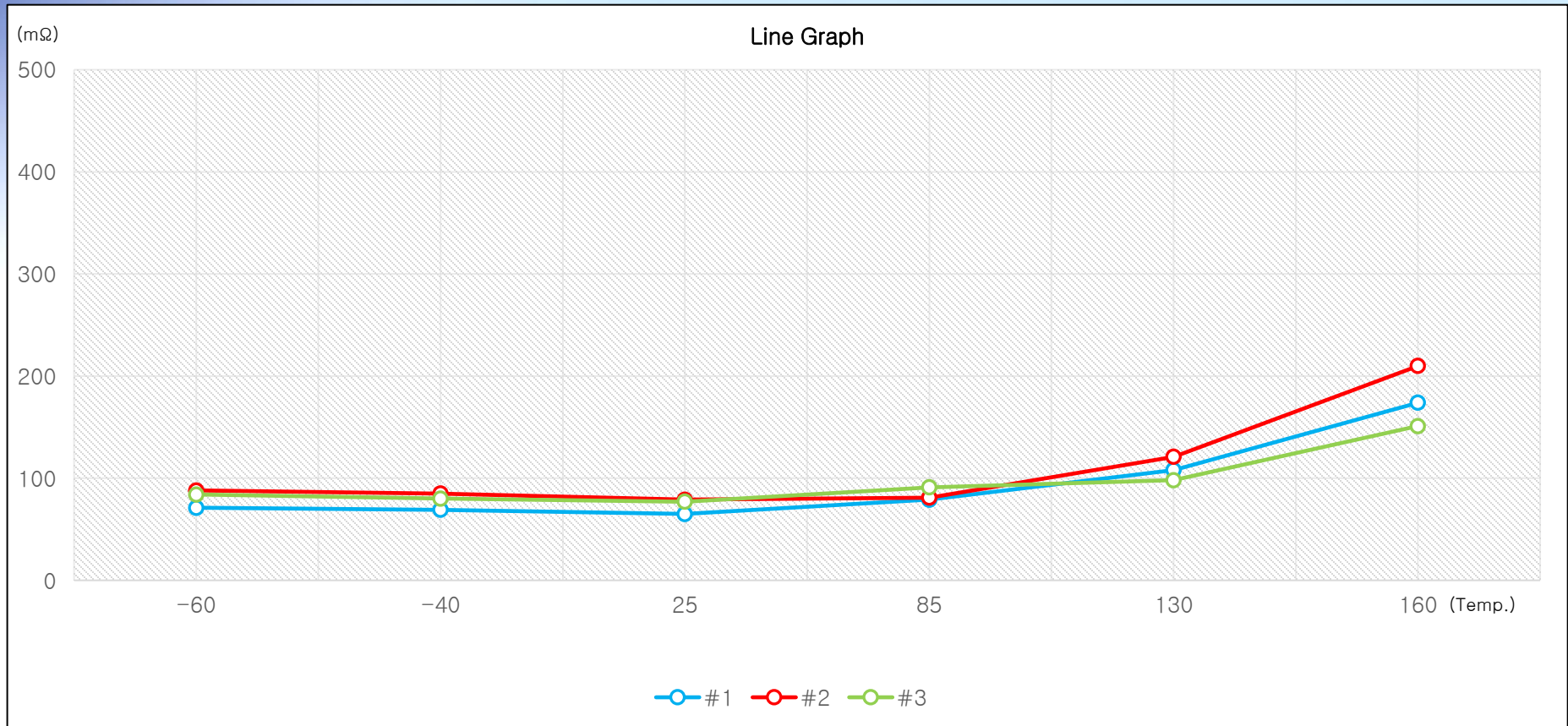


3. Test result

Pitch (mm)	0.30	0.35	0.4	0.5	0.8
Socket Height (mm)	0.47	0.5	0.57	0.76	0.92
Stroke(mm)	0.12	0.12	0.12	0.15	0.2
Current (A)	3.2	3.3	4.0	4.3	4.5

PRODUCTS _ Temperature Performance

Products maintain stable resistance both in high temperature and low temperature environment, so they have excellent durability.



* Maintaining Temperature for 30min at each temp

✓ At above 125°C, 30% higher press force is recommended than initial setting force at below 125°C

PRODUCTS _ Features

Outstanding contact stability

- Wide touch with package ball or pad
- Low contact resistance(less 100mΩ)

Hi-Frequency

- Very low socket height
(Thickness Range 0.35~2.2mm)
- Shorten transition time

Hi-Pin Count

- Over 10,000 pins available
- Different shape conductors at single socket

Fine Pitch

- 0.2mm pitch socket is qualified
- 0.15mm pitch socket(O/S test) is possible
- Fine pitch hole shaping by laser drilling technology

Low Cost

- Low cost Rubber socket
- Simple architecture

No Ball Damage

- Soft touch on device ball

PRODUCTS _ Features

By using laser processing equipment , fine hole and various types of molding can be done easily and quickly.
The conductor injection technology shows excellent performance both in DC&AC.
Precise and fast process expedite deliveries to customers.

Item			Rubber socket	
			Spec.	Condition
Quality	Contact Resistance		100mΩ ↓	Initial
	Frequency Range(-1.0dB)		30GHz ↑	0.8P=30GHz↑,0.5P=40GHz↑ 0.4P=40GHz↑,0.3P=40GHz↑
	Current Rating		3A ↑	-
	Contact Force		10~50g.f/Pin	-
	Temperature		-55°C ~ 150°C	-
	Life Span	Ball	10K~200K↑	0.3P~0.8P
		Pad(Land)	100K~500K↑	-
Cost	Unit Price		1/2 (Rubber/POGO)	
Delivery	Shipment		Initial : 3Weeks , Repeat : 3Days~2Weeks	

PRODUCTS _ Features

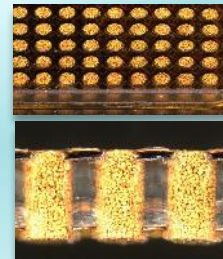
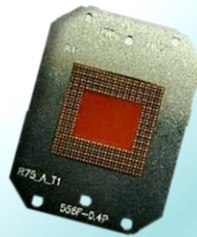
■ PCR vs POGO

Item			Rubber socket(PCR)		Spring probe(POGO)	
			Spec.	Condition	Spec.	Condition
Quality	Contact Resistance		100mΩ ↓	Initial	150mΩ ↓	Initial
	Frequency Range(-1.0dB)		40GHz ↑	0.4P	11GHz	0.4P, L=5.7mm
	Current Rating		3A ↑		1A	
	Contact Force		10~15g.f/Pin		20~30g.f/Pin	
	Temperature		-55 ~ 150°C		-40 ~ 125°C	
	Life Span	Ball	30K	0.4P BGA	50K	0.4P BGA
		Pad(Land)	80K↑		100K	
Cost	Unit Price		X1/2 ~ 2/3		1 ~ 2 USD	
Delivery	Production capability (0.3p 200pin)		1,000EA/1Day/1Machine		?	

PRODUCTS _ Features

PCR

■ PCR vs POGO



Strong Point

Low cost

Laser hole piercing
Molding

High Frequency

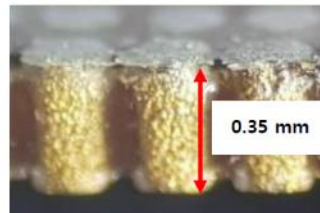
Thin Thickness
Many contact point

No ball damage

Soft contact
No ball mark

Wide Temp.

-55°C ~ 150°C
Specialized at low temp.



Weak Point

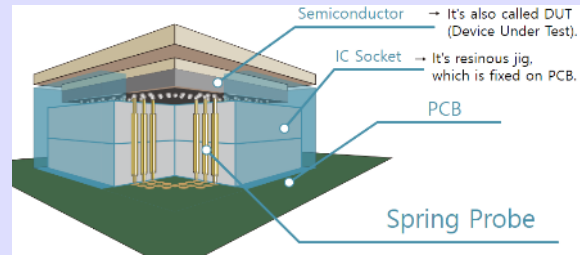
Elasticity

Life Span

Silicone

PRODUCTS _ Features

POGO PIN



■ PCR vs POGO

Strong Point

Life Span

Mechanical

Elasticity

Spring

Weak Point

Ball damage

Ball mark

Expensive

Many Parts
Machining

Signal Path

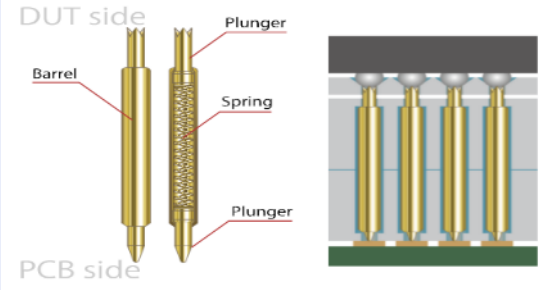
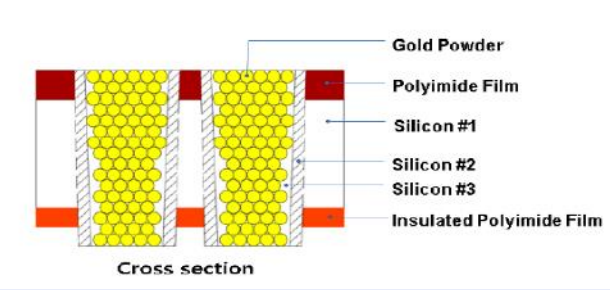
Assembly
Thickness Limited

Temp.

-40°C ~ 125°C
Poor performance
under -40°C



■ PCR vs POGO

Item	POGO PIN	PCR
Parts	Spring, Barrel, Plunger, Housing	Silicone, Gold Powder, Frame(SUS or FR4)
Contact Point	Plunger(Machining)	Gold Powder(atomizing)
Actuation	Spring	Silicone
Structure	 <p>The diagram illustrates the POGO PIN structure. On the left, a single pin is shown with labels for 'Barrel', 'Plunger', and 'Spring'. On the right, a cross-section of multiple pins is shown, with labels for 'DUT side' and 'PCB side'.</p>	 <p>The diagram illustrates the PCR structure. It shows a cross-section of the device with labels for 'Gold Powder', 'Polyimide Film', 'Silicon #1', 'Silicon #2', 'Silicon #3', and 'Insulated Polyimide Film'. The text 'Cross section' is also present.</p>

PRODUCTS _ Features

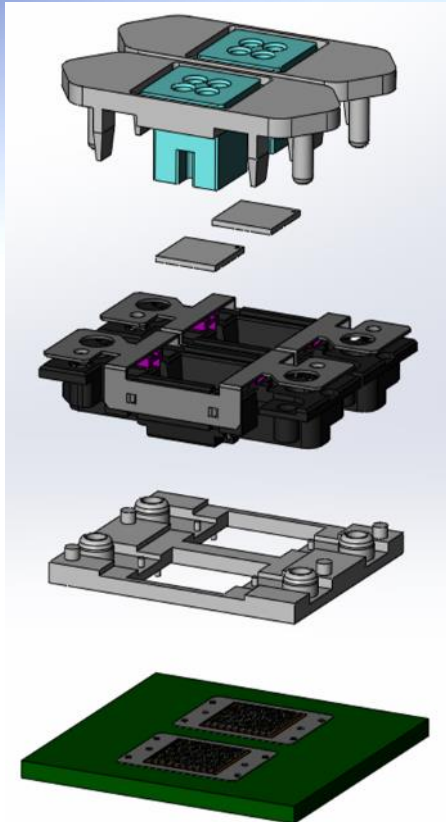
Core tool	Laser piercing machine
Core technology	Laser hole piercing & Conductor filling
Merits	<ul style="list-style-type: none"> ✓ Filling conductor after laser hole fabrication → Expedite delivery ✓ Simplified molding → Low cost

■ Technical competitiveness

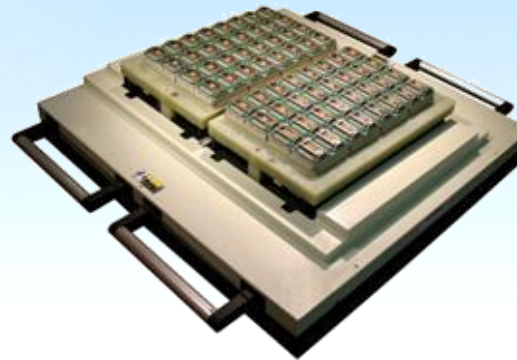
Item		MFM (Competitor)	LHF (MSL)
Quality	Fine pitch forming	Difficulty	Easy
	Thickness / (Stroke) control	<	
	Metal powder residue	Remain	None
	Electrical performance	<	
Cost	Tooling cost	>	
	Manufacturing cost	>	
Delivery	Tooling	Long	Short
	Lead time	Long	Short
	Production Capa.(0.3p 200pin)	?	1,000EA / 1Day/1Machine

PRODUCTS _ Application

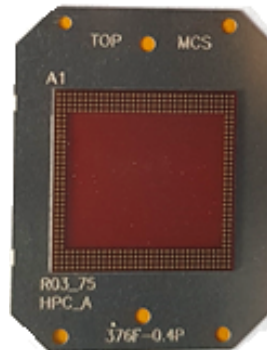
ATE Test Solution



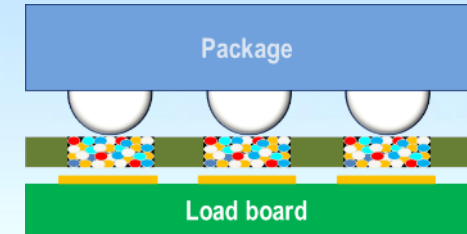
C.O.K



Hi-Fix



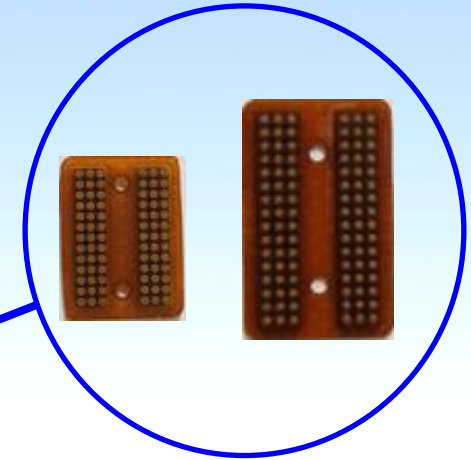
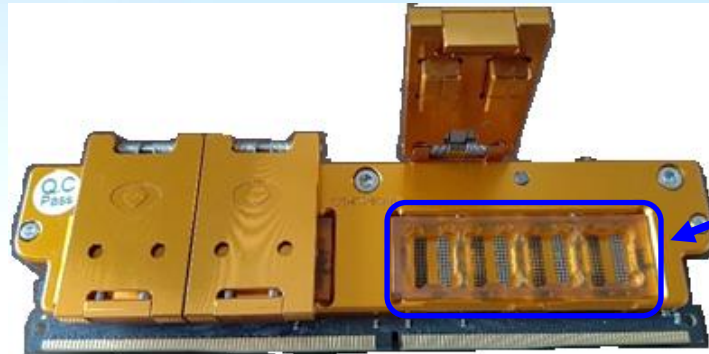
Rubber Socket



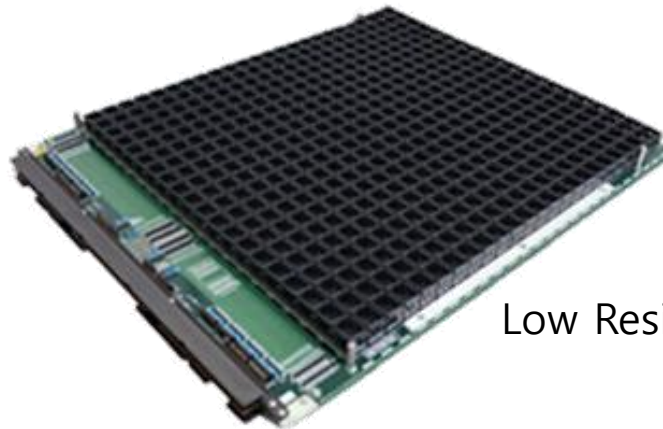
Handler

PRODUCTS _ Application

Manual Test Solution



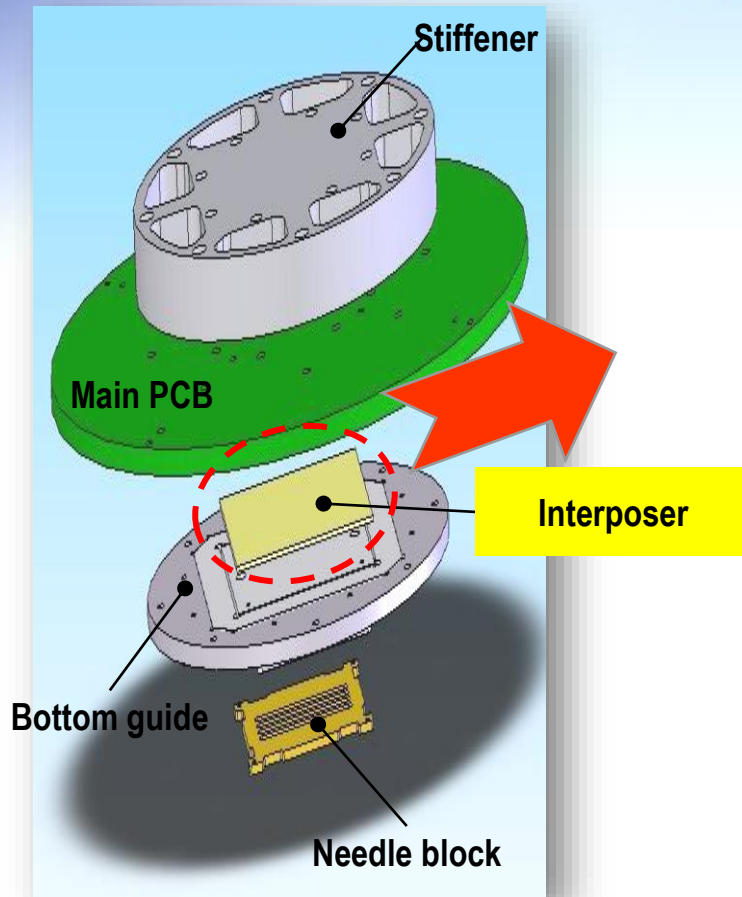
Burn-In Test Solution



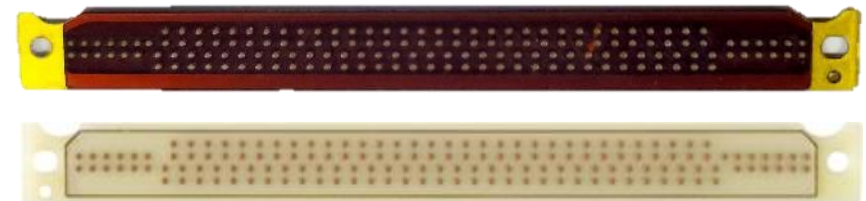
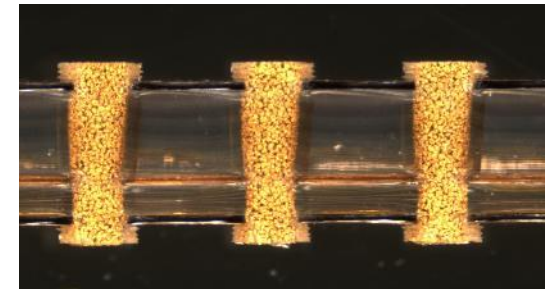
Low Resistance($100\text{m}\Omega \downarrow$) @125°C

PRODUCTS _ Application

Interposer Solution



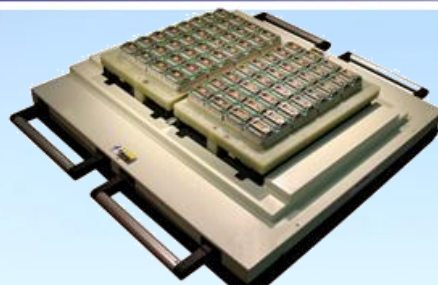
- Stabilized contact
- No contact damage
- Wider contact
- Easy replacement
- Customized design



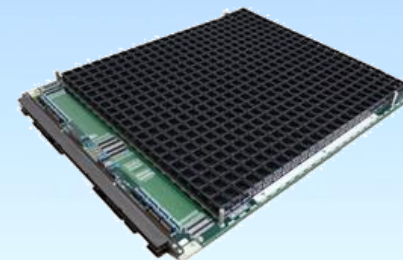
PRODUCTS _ Application



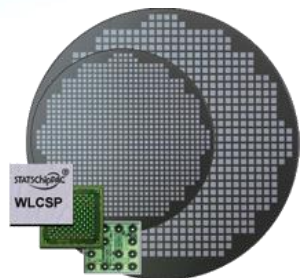
Logic handler test



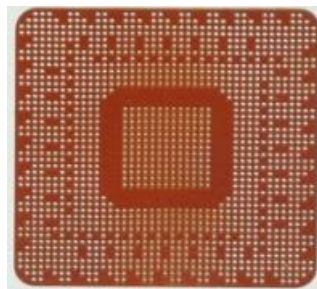
Memory handler test



Burn-in test



Fine pitch test



Function test



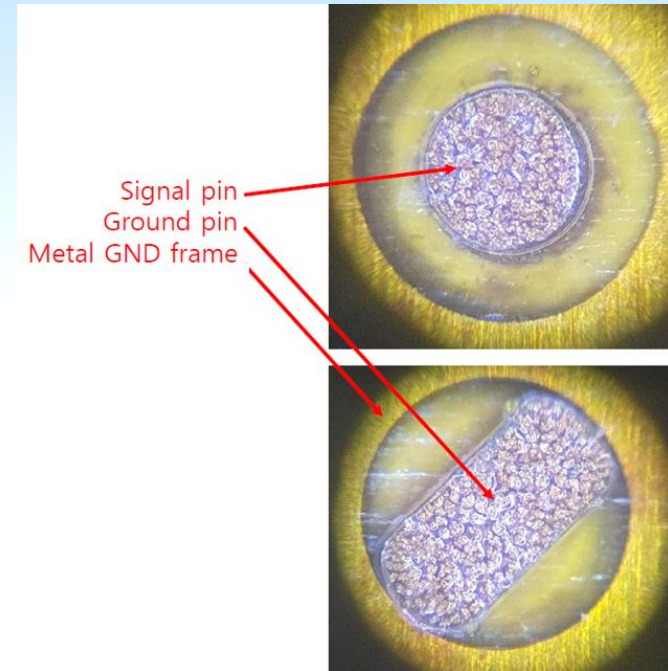
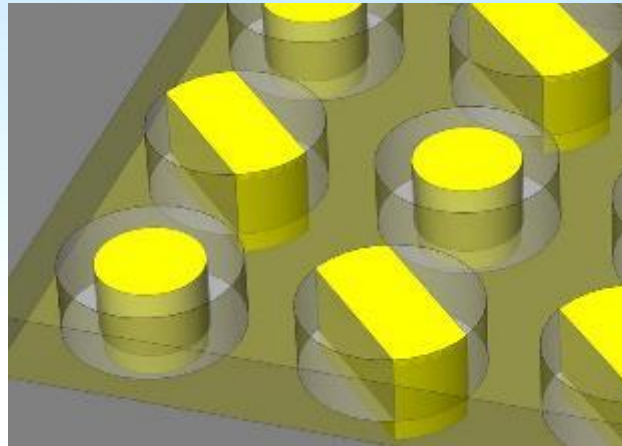
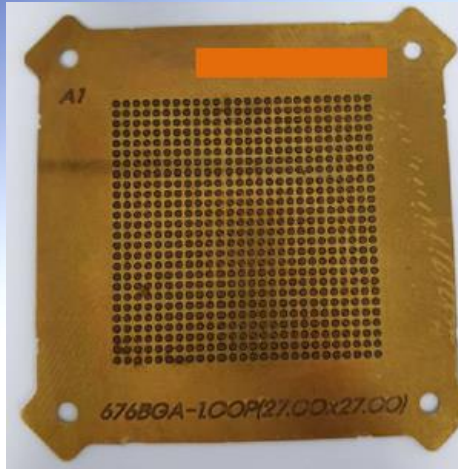
High frequency test



Reliability test

PRODUCTS _ Special PCR

❖ Coaxial Socket

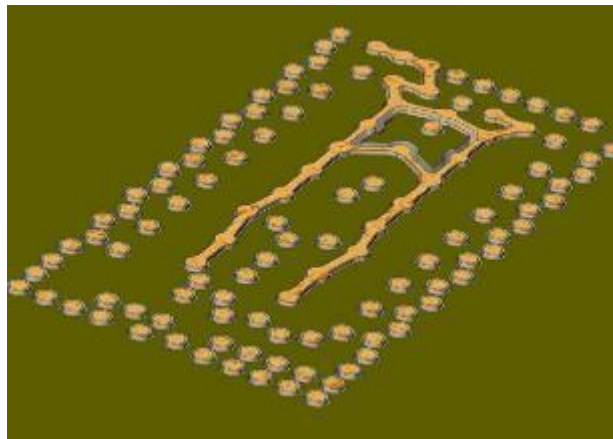
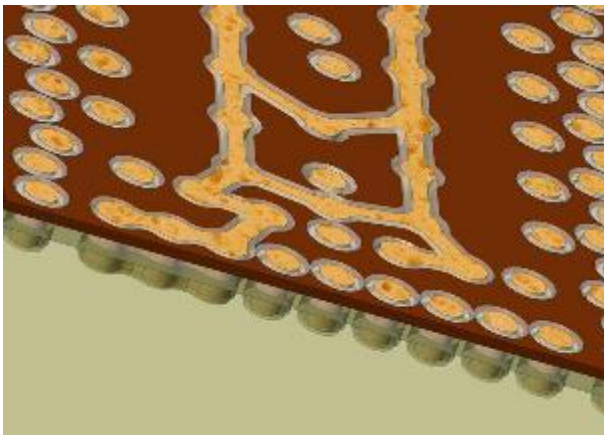
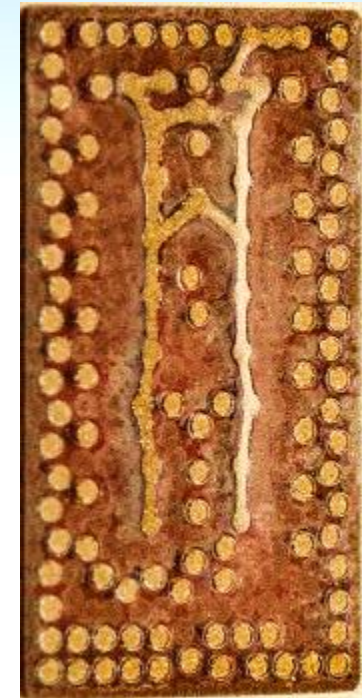
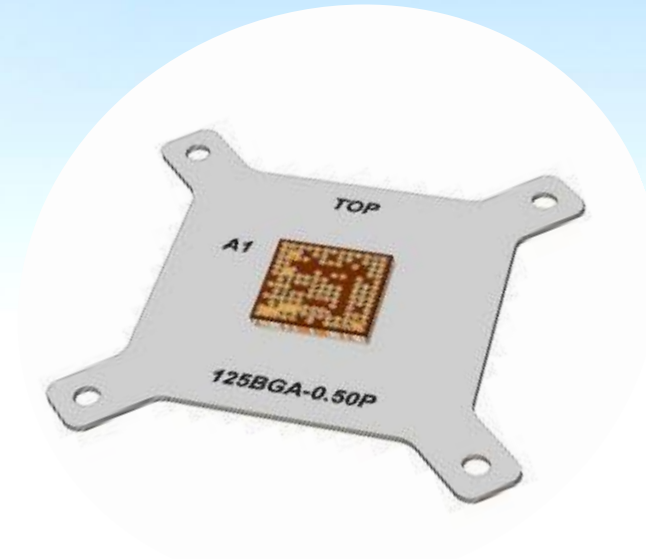


▷ GND pins are shorted with metal frame electrically

PRODUCTS _ Special PCR

❖ Isolation Socket

Ladar application (60GHz ~ 80GHz)



PRODUCTS _ Special PCR

